

GM40001A IST COUPON INFORMATION (Micro Via)

(With capacitance holes)

This package contains design files for a generic Interconnect Stress Test (IST) Test Coupon containing **Plated Through Hole and 2 layer Micro via technologies**, on a 5.0" (126.9mm) X 0.6" (15.2mm) coupon, with a total thickness up to .125" (3.2mm) and limited to a minimum of 6 layers. This coupon is designed on a small grid, .040" (1mm). The maximum drilled hole is .015" (.38mm) and pad size is .026" (.66mm) for both power and sense 1 circuit and vias ablated with .006" (.15mm) with .018" (.46mm) for sense 2 circuit); decreasing these feature sizes will not affect the coupon functionality but increasing these feature sizes may result in shorts or excessively small clearances. Instructions on how to create a custom IST coupon for a specific product are included.

Note: The GM40000A design is limited to 2 layer micro vias on either side of the substrate. If it is required to produce more than 2 layer micro vias, contact PWB for a customized design.

